

What is claimed is:

1. A method of ablating holes in a material, comprising:

providing a laminated material comprising first and second layers, said first and second  
5 layers having different coefficients of thermal expansion, said first layer having within it a hole,  
wherein a target region of said second layer in said laminated material is not laminated to said  
first layer but is surrounded entirely by laminated regions wherein the first layer is laminated to  
the second layer;

providing a laser source producing energy of a wavelength and a power level that can  
10 ablate material from said first layer;

changing the temperature of the laminated material so as to place said target region  
under tension;

directing said laser source onto said target region and ablating a portion thereof.

2. The method of claim 1, wherein the coefficient of thermal expansion of the first  
15 laminate layer is greater than that of the second laminate layer.

3. The method of claim 1, wherein the coefficient of thermal expansion of the second  
20 laminate layer is greater than that of the first laminate layer.

4. A method of preparing a laminated material for laser ablation, comprising:  
laminating a first layer to a second layer, wherein said first and second layers have  
different coefficients of thermal expansion, and wherein said second layer has an interior hole  
such that when the laminated substrate is formed, a region of the first layer aligned with said hole  
25 is not laminated to the second layer and is surrounded by laminated regions.

5. A laminated material comprising first and second layers, wherein said first and  
second layers have different coefficients of thermal expansion, and wherein said second layer has  
an interior hole such that a region of the first layer aligned with said hole is not laminated to the  
30 second layer and is surrounded by laminated regions.